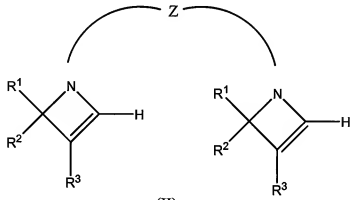
AMENDMENTS TO THE CLAIMS:

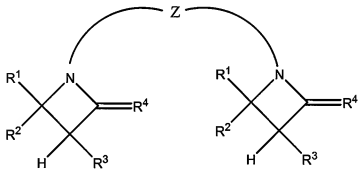
This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Previously Presented) An azetidine derivative of the general formula (II) or (III)



(II)



(III)

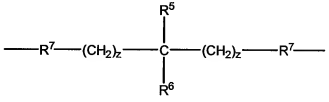
where

R^1, R^2 and R^3 independently of one another are H,

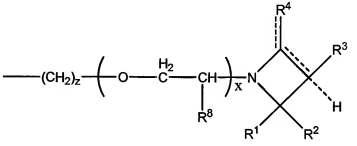
C_1-C_{20} alkyl, C_3-C_8 cycloalkyl, C_6-C_{10} aryl or alkylaryl with C_1-C_4 alkyl and C_6-C_{10} aryl groups

R^4 = H, C_1-C_6 alkyl (idene)

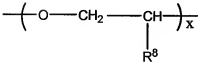
Z = C_2-C_{25} alkylidene, C_5-C_{25} cycloalkylidene, C_6-C_{24} arylene and also



R^5 and R^6 = H, CH_2OH, C_1-C_4 alkyl, C_6H_5,



R^7 =



R^8 = H, CH_3, C_2H_5, C_6H_5

z = 0 or 1

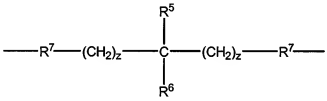
x = 0 to 100.

2. (Canceled)

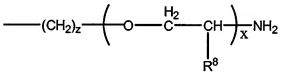
3. (Canceled)

4. (Withdrawn) A method for producing an azetidine derivative of claim 1, wherein a polyamine of the formula NH_2-Z'-NH_2 is reacted with an α,β-unsaturated aldehyde of the formula R^1R^2–C=CR^3CHO or with an α,β-unsaturated ketone of the formula R^1R^2C=CR^3–COR^4 in the temperature range from 20 to 150°C, where Z' is

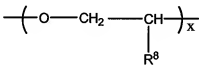
C_2-C_{25} alkylidene, C_5-C_{25} cycloalkylidene, C_6-C_{24} arylene, and



R^5 and R^6 = H, CH_2OH, C_1-C_4 alkyl, C_6H_5,



R^7 =



R^8 = H, CH_3, C_2H_5, C_6H_5

z = 0 or 1

x = 0 to 100

and R^1, R^2, R^3, and R^4 possess the above definition.

5. (Withdrawn) The method of claim 4, wherein the reaction is carried out in the presence of an organic solvent, especially toluene.

6. (Withdrawn) The use of an azetidine derivative of claim 1 as a latent curing component for resins having functional groups which are reactive toward amino groups.

7. (Withdrawn) The use of claim 6, wherein the azetidine derivative of the formula (II) and/or (III) is mixed with the resin to be cured, the azetidine ring is hydrolytically opened by moisture exposure, and the secondary amine formed is caused to react with the reactive functional groups of the resin to be cured.

8. (Withdrawn) The use of claim 6, wherein polyurethanes or polyepoxides and also mixtures thereof are used as resin to be cured.

9. (Withdrawn) The use of claim 6 wherein the curing component is used an amount of 0.01% to 150% by weight, in particular 0.1% to 20% by weight, based on the amount of the resin to be cured.

10. (Withdrawn) The use of claim 6 wherein the mixture consisting of curing component and resin is cured at a temperature of 5 to 80°C and optionally in the presence of a suitable catalyst.

11. (Withdrawn) The use of claim 6 wherein the curing component is used in the production of (floor) coatings, sealants, and adhesives.